

Board Level Cooling – Extruded 5080



BOARD LEVEL COOLING – Extruded 5080

Extruded 5080 is a series of rectangular bi-directional board level heat sinks designed to cool DIP 24 and DIP 40 devices. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
508500B00000G	DIP 24
508700B00000G	DIP 40

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	13.46
Heat Sink Length (mm)	See "A" Dim below
Heat Sink Height (mm)	4.83
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number	"A" Dim
508500B00000G	31.75
508700B00000G	50.80

